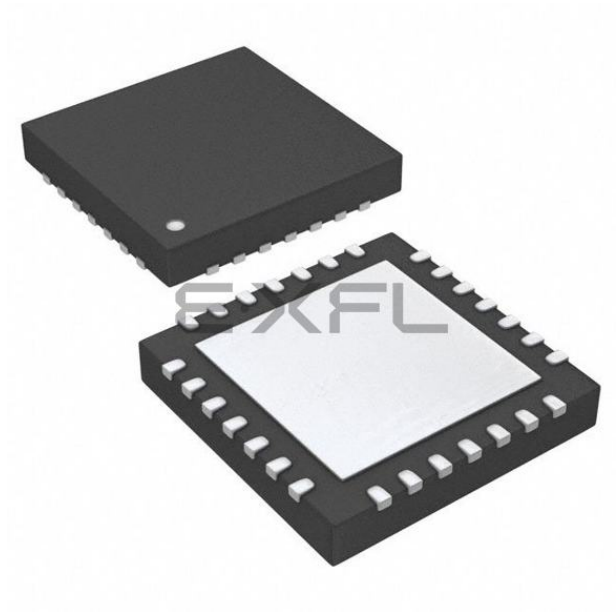

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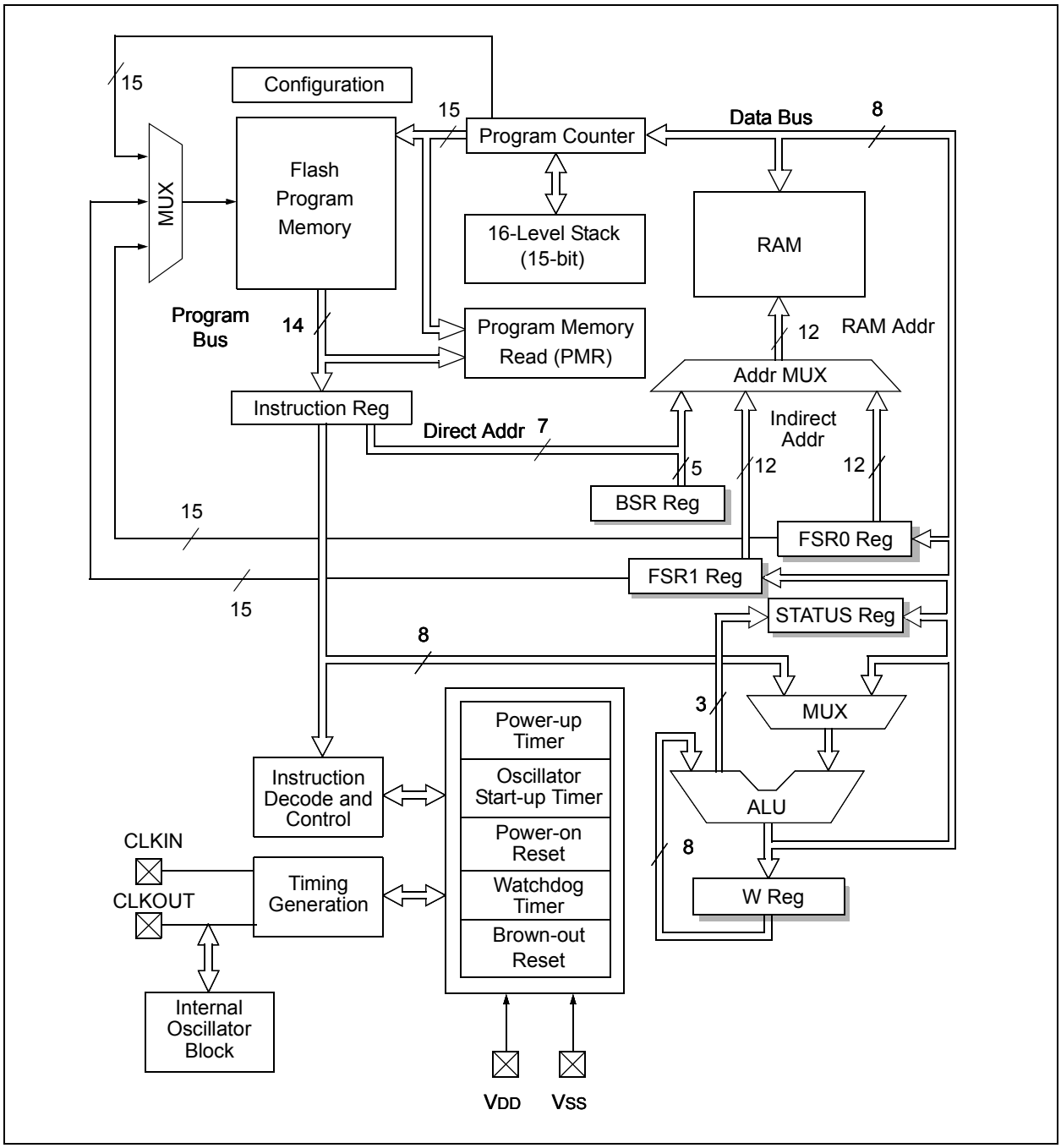
What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	20MHz
Connectivity	-
Peripherals	Brown-out Detect/Reset, LCD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	3.5KB (2K x 14)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.6V
Data Converters	A/D 11x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-UFQFN Exposed Pad
Supplier Device Package	28-UQFN (4x4)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lf1902t-i-mv

FIGURE 2-1: CORE BLOCK DIAGRAM



3.0 MEMORY ORGANIZATION

These devices contain the following types of memory:

- Program Memory
  - Configuration Words
  - Device ID
  - User ID
  - Flash Program Memory
- Data Memory
  - Core Registers
  - Special Function Registers
  - General Purpose RAM
  - Common RAM

The following features are associated with access and control of program memory and data memory:

- PCL and PCLATH
- Stack
- Indirect Addressing

3.1 Program Memory Organization

The enhanced mid-range core has a 15-bit program counter capable of addressing 32K x 14 program memory space. Table 3-1 shows the memory sizes implemented for the PIC16LF1902/3 family. Accessing a location above these boundaries will cause a wrap-around within the implemented memory space. The Reset vector is at 0000h and the interrupt vector is at 0004h (see Figures 3-1, and 3-2).

TABLE 3-1: DEVICE SIZES AND ADDRESSES

Device	Program Memory Space (Words)	Last Program Memory Address	High-Endurance Flash Memory Address Range(1)
PIC16LF1902	2,048	07FFh	0780h-07FFh
PIC16LF1903	4,096	0FFFh	0F80h-0FFFh

Note 1: High-endurance Flash applies to low byte of each address in the range.

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FIGURE 3-6: ACCESSING THE STACK EXAMPLE 2

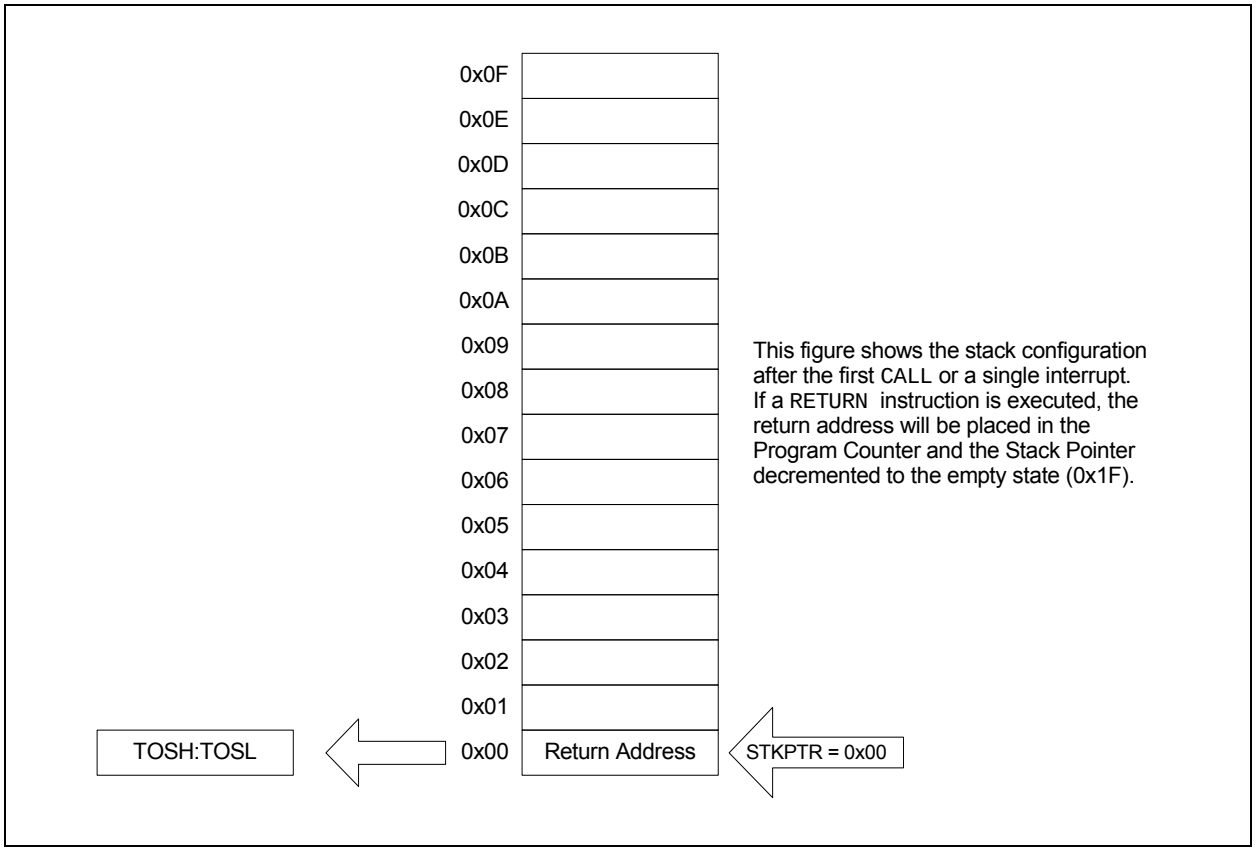
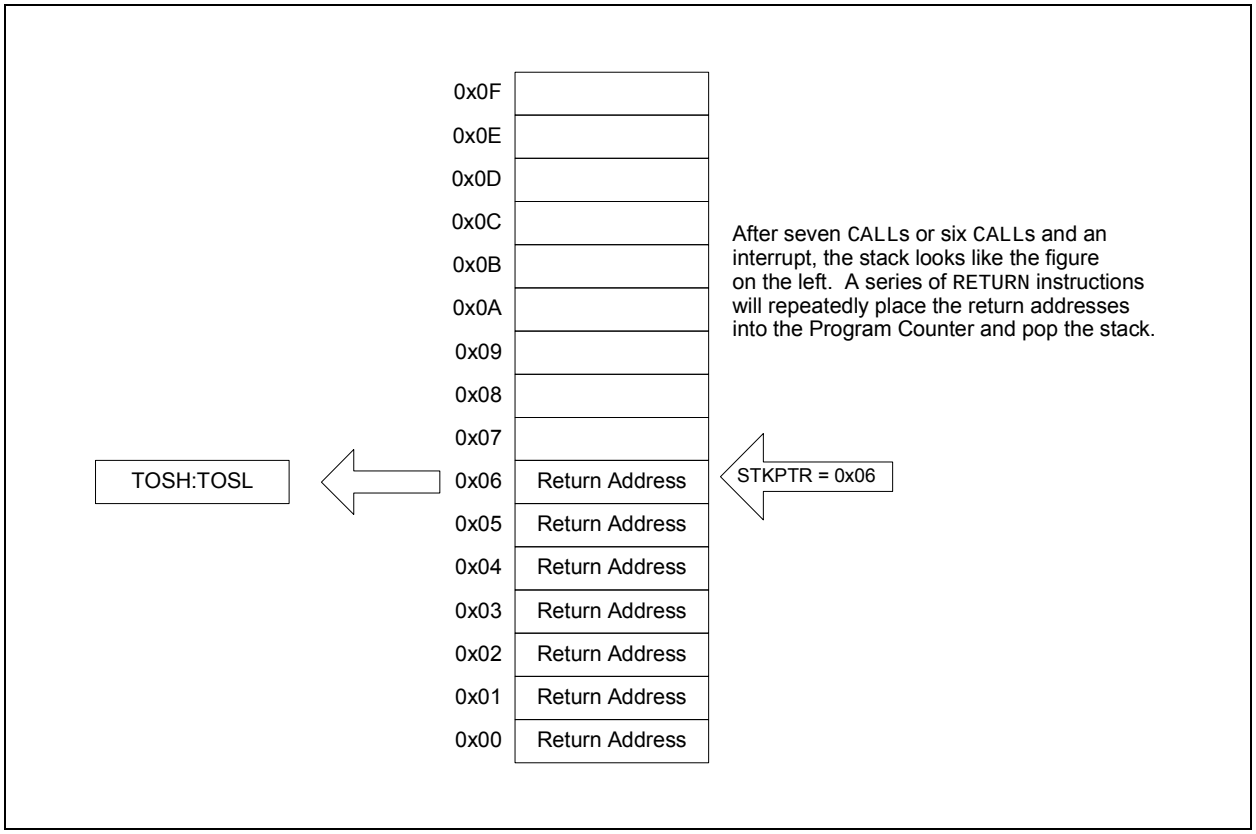


FIGURE 3-7: ACCESSING THE STACK EXAMPLE 3



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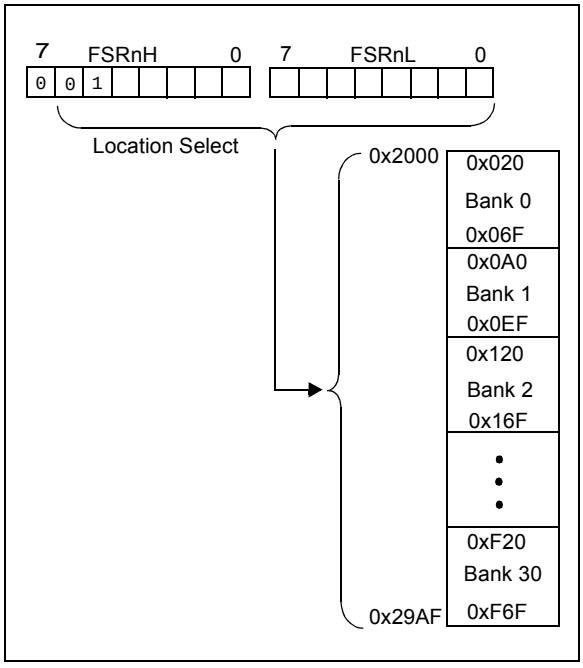
3.5.2 LINEAR DATA MEMORY

The linear data memory is the region from FSR address 0x2000 to FSR address 0x29AF. This region is a virtual region that points back to the 80-byte blocks of GPR memory in all the banks.

Unimplemented memory reads as 0x00. Use of the linear data memory region allows buffers to be larger than 80 bytes because incrementing the FSR beyond one bank will go directly to the GPR memory of the next bank.

The 16 bytes of common memory are not included in the linear data memory region.

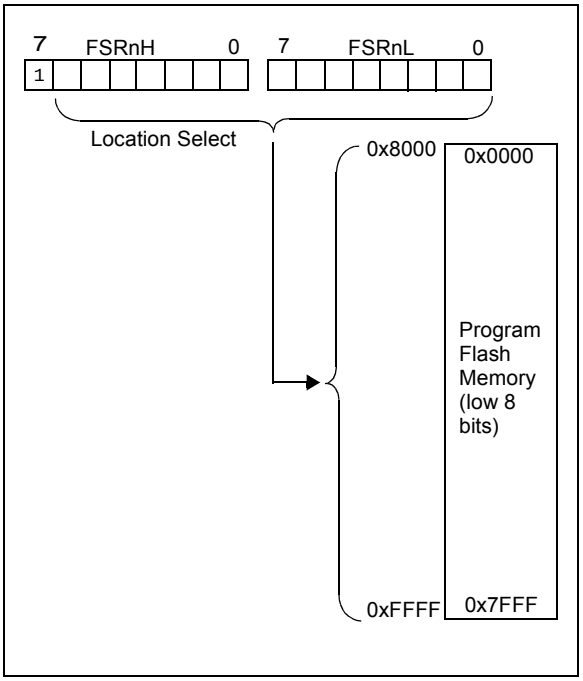
FIGURE 3-11: LINEAR DATA MEMORY MAP



3.5.3 PROGRAM FLASH MEMORY

To make constant data access easier, the entire program Flash memory is mapped to the upper half of the FSR address space. When the MSB of FSRnH is set, the lower 15 bits are the address in program memory which will be accessed through INDF. Only the lower eight bits of each memory location is accessible via INDF. Writing to the program Flash memory cannot be accomplished via the FSR/INDF interface. All instructions that access program Flash memory via the FSR/INDF interface will require one additional instruction cycle to complete.

FIGURE 3-12: PROGRAM FLASH MEMORY MAP



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9.1 Independent Clock Source

The WDT derives its time base from the 31 kHz LFINTOSC internal oscillator. Time intervals in this chapter are based on a nominal interval of 1 ms. See **Section 21.0 "Electrical Specifications"** for the LFINTOSC tolerances.

9.2 WDT Operating Modes

The Watchdog Timer module has four operating modes controlled by the WDTE<1:0> bits in Configuration Word 1. See Table 9-1.

9.2.1 WDT IS ALWAYS ON

When the WDTE bits of Configuration Word 1 are set to '11', the WDT is always on.

WDT protection is active during Sleep.

9.2.2 WDT IS OFF IN SLEEP

When the WDTE bits of Configuration Word 1 are set to '10', the WDT is on, except in Sleep.

WDT protection is not active during Sleep.

9.2.3 WDT CONTROLLED BY SOFTWARE

When the WDTE bits of Configuration Word 1 are set to '01', the WDT is controlled by the SWDTEN bit of the WDTCON register.

WDT protection is unchanged by Sleep. See Table 9-1 for more details.

TABLE 9-1: WDT OPERATING MODES

WDTE<1:0>	SWDTEN	Device Mode	WDT Mode
11	X	X	Active
10	X	Awake	Active
		Sleep	Disabled
01	1	X	Active
	0		Disabled
00	X	X	Disabled

9.3 Time-Out Period

The WDTPS bits of the WDTCON register set the time-out period from 1 ms to 256 seconds (nominal). After a Reset, the default time-out period is two seconds.

9.4 Clearing the WDT

The WDT is cleared when any of the following conditions occur:

- Any Reset
- CLRWDT instruction is executed
- Device enters Sleep
- Device wakes up from Sleep
- Oscillator fail event
- WDT is disabled

See Table 9-2 for more information.

9.5 Operation During Sleep

When the device enters Sleep, the WDT is cleared. If the WDT is enabled during Sleep, the WDT resumes counting.

When the device exits Sleep, the WDT is cleared again.

When a WDT time-out occurs while the device is in Sleep, no Reset is generated. Instead, the device wakes up and resumes operation. The $\overline{TO}$ and $\overline{PD}$ bits in the STATUS register are changed to indicate the event. See **Section 3.0 "Memory Organization"** and STATUS register (**Register 3-1)** for more information.

TABLE 9-2: WDT CLEARING CONDITIONS

Conditions	WDT
WDTE<1:0> = 00	Cleared
WDTE<1:0> = 01 and SWDTEN = 0	
WDTE<1:0> = 10 and enter Sleep	
CLRWDT Command	
Oscillator Fail Detected	
Exit Sleep + System Clock = T1OSC, EXTRC, INTOSC, EXTCLK	
Change INTOSC divider (IRCF bits)	Unaffected

TABLE 9-3: SUMMARY OF REGISTERS ASSOCIATED WITH WATCHDOG TIMER

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
OSCCON	—	IRCF<3:0>				—	SCS<1:0>		53
STATUS	—	—	—	$\overline{TO}$	$\overline{PD}$	Z	DC	C	16
WDTCON	—	—	WDTPS<4:0>					SWDTEN	70

Legend: x = unknown, u = unchanged, – = unimplemented locations read as '0'. Shaded cells are not used by Watchdog Timer.

TABLE 9-4: SUMMARY OF CONFIGURATION WORD WITH WATCHDOG TIMER

Name	Bits	Bit -/7	Bit -/6	Bit 13/5	Bit 12/4	Bit 11/3	Bit 10/2	Bit 9/1	Bit 8/0	Register on Page
CONFIG1	13:8	—	—	—	—	$\overline{CLKOUTEN}$	BOREN<1:0>		—	34
	7:0	$\overline{CP}$	MCLRE	$\overline{PWRTE}$	WDTE<1:0>		—	FOSC<1:0>		

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by Watchdog Timer.

11.0 I/O PORTS

In general, when a peripheral is enabled on a port pin, that pin cannot be used as a general purpose output. However, the pin can still be read.

Each port has three standard registers for its operation. These registers are:

- TRISx registers (data direction)
- PORTx registers (reads the levels on the pins of the device)
- LATx registers (output latch)

Some ports may have one or more of the following additional registers. These registers are:

- ANSELx (analog select)
- WPUx (weak pull-up)

TABLE 11-1: PORT AVAILABILITY PER DEVICE

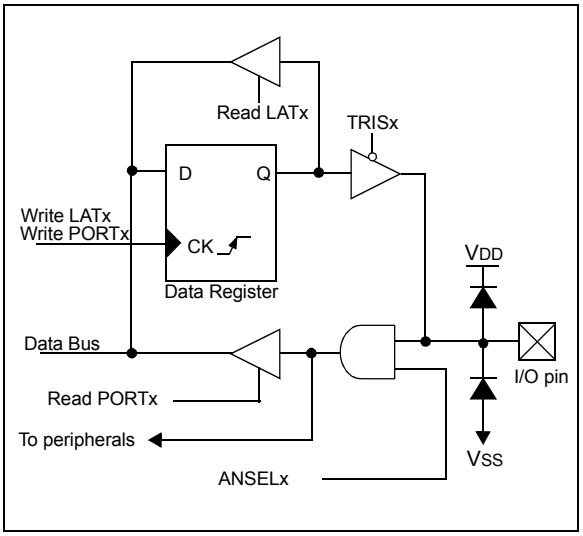
Device	PORTA	PORTB	PORTC	PORTE
PIC16LF1902/3	•	•	•	•

The Data Latch (LATA register) is useful for read-modify-write operations on the value that the I/O pins are driving.

A write operation to the LATA register has the same effect as a write to the corresponding PORTA register. A read of the LATA register reads of the values held in the I/O PORT latches, while a read of the PORTA register reads the actual I/O pin value.

Ports that support analog inputs have an associated ANSELx register. When an ANSEL bit is set, the digital input buffer associated with that bit is disabled. Disabling the input buffer prevents analog signal levels on the pin between a logic high and low from causing excessive current in the logic input circuitry. A simplified model of a generic I/O port, without the interfaces to other peripherals, is shown in Figure 11-1.

FIGURE 11-1: GENERIC I/O PORT OPERATION



EXAMPLE 11-1: INITIALIZING PORTA

```
; This code example illustrates
; initializing the PORTA register. The
; other ports are initialized in the same
; manner.

BANKSEL  PORTA       ;
CLRF     PORTA       ;Init PORTA
BANKSEL  LATA        ;Data Latch
CLRF     LATA        ;
BANKSEL  ANSELA      ;
CLRF     ANSELA      ;digital I/O
BANKSEL  TRISA       ;
MOVLW    B'00111000' ;Set RA<5:3> as inputs
MOVWF    TRISA       ;and set RA<2:0> as
                     ;outputs
```


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TABLE 11-8: SUMMARY OF REGISTERS ASSOCIATED WITH PORTC

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
LATC	LATC7	LATC6	LATC5	LATC4	LATC3	LATC2	LATC1	LATC0	93
PORTC	RC7	RC6	RC5	RC4	RC3	RC2	RC1	RC0	93
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	93

Legend: x = unknown, u = unchanged, - = unimplemented locations read as '0'. Shaded cells are not used by PORTC.

15.2.5 A/D CONVERSION PROCEDURE

This is an example procedure for using the ADC to perform an Analog-to-Digital conversion:

1. Configure Port:
   - Disable pin output driver (Refer to the TRIS register)
   - Configure pin as analog (Refer to the ANSEL register)
2. Configure the ADC module:
   - Select ADC conversion clock
   - Configure voltage reference
   - Select ADC input channel
   - Turn on ADC module
3. Configure ADC interrupt (optional):
   - Clear ADC interrupt flag
   - Enable ADC interrupt
   - Enable peripheral interrupt
   - Enable global interrupt**(1)**
4. Wait the required acquisition time**(2)**.
5. Start conversion by setting the GO/$\overline{\text{DONE}}$ bit.
6. Wait for ADC conversion to complete by one of the following:
   - Polling the GO/$\overline{\text{DONE}}$ bit
   - Waiting for the ADC interrupt (interrupts enabled)
7. Read ADC Result.
8. Clear the ADC interrupt flag (required if interrupt is enabled).

Note 1: The global interrupt can be disabled if the user is attempting to wake-up from Sleep and resume in-line code execution.

2: Refer to **Section 15.3 "A/D Acquisition Requirements"**.

EXAMPLE 15-1: A/D CONVERSION

```
;This code block configures the ADC
;for polling, Vdd and Vss references, Frc
;clock and AN0 input.
;
;Conversion start & polling for completion
; are included.
;
BANKSEL   ADCON1       ;
MOVLW     B'11110000'  ;Right justify, Frc
                       ;clock
MOVWF     ADCON1       ;Vdd and Vss Vref
BANKSEL   TRISA        ;
BSF       TRISA,0      ;Set RA0 to input
BANKSEL   ANSEL        ;
BSF       ANSEL,0      ;Set RA0 to analog
BANKSEL   ADCON0       ;
MOVLW     B'00000001'  ;Select channel AN0
MOVWF     ADCON0       ;Turn ADC On
CALL      SampleTime   ;Acquisiton delay
BSF       ADCON0,ADGO  ;Start conversion
BTFSC     ADCON0,ADGO  ;Is conversion done?
GOTO      $-1          ;No, test again
BANKSEL   ADRESH       ;
MOVF      ADRESH,W     ;Read upper 2 bits
MOVWF     RESULTHI     ;store in GPR space
BANKSEL   ADRESL       ;
MOVF      ADRESL,W     ;Read lower 8 bits
MOVWF     RESULTLO     ;Store in GPR space
```

15.3 A/D Acquisition Requirements

For the ADC to meet its specified accuracy, the charge holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The Analog Input model is shown in Figure 15-4. The source impedance (RS) and the internal sampling switch (RSS) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (RSS) impedance varies over the device voltage (VDD), refer to Figure 15-4. **The maximum recommended impedance for analog sources is 10 kΩ.** As the source impedance is decreased, the acquisition time may be decreased. After the analog input channel is selected (or changed), an A/D acquisition must be done before the conversion can be started. To calculate the minimum acquisition time, Equation 15-1 may be used. This equation assumes that 1/2 LSb error is used (1,024 steps for the ADC). The 1/2 LSb error is the maximum error allowed for the ADC to meet its specified resolution.

EQUATION 15-1: ACQUISITION TIME EXAMPLE

Assumptions: $Temperature = 50°C$ *and external impedance of* $10k\Omega$ *5.0V* V_{DD}

$$T_{ACQ} = \text{Amplifier Settling Time} + \text{Hold Capacitor Charging Time} + \text{Temperature Coefficient}$$
$$= T_{AMP} + T_C + T_{COFF}$$
$$= 2\mu s + T_C + [(Temperature - 25°C)(0.05\mu s/°C)]$$

The value for T_C *can be approximated with the following equations:*

$$V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right) = V_{CHOLD}$$;[1] V_{CHOLD} *charged to within 1/2 lsb*

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{CHOLD}$$;[2] V_{CHOLD} *charge response to* $V_{APPLIED}$

$$V_{APPLIED}\left(1 - e^{\frac{-T_C}{RC}}\right) = V_{APPLIED}\left(1 - \frac{1}{(2^{n+1}) - 1}\right)$$;combining [1] and [2]

Note: Where n = number of bits of the ADC.

Solving for T_C*:*

$$T_C = -C_{HOLD}(R_{IC} + R_{SS} + R_S)\ ln(1/2047)$$
$$= -12.5pF(1k\Omega + 7k\Omega + 10k\Omega)\ ln(0.0004885)$$
$$= 1.715\mu s$$

Therefore:

$$T_{ACQ} = 2\mu s + 1.715\mu s + [(50°C - 25°C)(0.05\mu s/°C)]$$
$$= 4.96\mu s$$

Note 1: The reference voltage (VREF) has no effect on the equation, since it cancels itself out.

2: The charge holding capacitor (CHOLD) is not discharged after each conversion.

3: The maximum recommended impedance for analog sources is 10 kΩ. This is required to meet the pin leakage specification.

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TABLE 17-5: SUMMARY OF REGISTERS ASSOCIATED WITH TIMER1

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Register on Page
INTCON	GIE	PEIE	TMR0IE	INTE	IOCIE	TMR0IF	INTF	IOCIF	60
PIE1	TMR1GIE	ADIE	—	—	—	—	—	TMR1IE	61
PIR1	TMR1GIF	ADIF	—	—	—	—	—	TMR1IF	63
TMR1H	Holding Register for the Most Significant Byte of the 16-bit TMR1 Register								126*
TMR1L	Holding Register for the Least Significant Byte of the 16-bit TMR1 Register								126*
TRISC	TRISC7	TRISC6	TRISC5	TRISC4	TRISC3	TRISC2	TRISC1	TRISC0	96
T1CON	TMR1CS1	TMR1CS0	T1CKPS<1:0>		T1OSCEN	$\overline{\text{T1SYNC}}$	—	TMR1ON	130
T1GCON	TMR1GE	T1GPOL	T1GTM	T1GSPM	$\overline{\text{T1GGO}}$/ $\overline{\text{DONE}}$	T1GVAL	T1GSS1	T1GSS0	131

Legend: — = unimplemented location, read as '0'. Shaded cells are not used by the Timer1 module.

* Page provides register information.

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REGISTER 18-7: LCDRL: LCD REFERENCE LADDER CONTROL REGISTERS

R/W-0/0	R/W-0/0	R/W-0/0	R/W-0/0	U-0	R/W-0/0	R/W-0/0	R/W-0/0
LRLAP<1:0>		LRLBP<1:0>		—	LRLAT<2:0>		
bit 7							bit 0

Legend:		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’
u = Bit is unchanged	x = Bit is unknown	-n/n = Value at POR and BOR/Value at all other Resets
‘1’ = Bit is set	‘0’ = Bit is cleared	

bit 7-6 **LRLAP<1:0>:** LCD Reference Ladder A Time Power Control bits
During Time interval A (Refer toFigure 18-4):
00 = Internal LCD Reference Ladder is powered down and unconnected
01 = Internal LCD Reference Ladder is powered in Low-Power mode
10 = Internal LCD Reference Ladder is powered in Medium-Power mode
11 = Internal LCD Reference Ladder is powered in High-Power mode

bit 5-4 **LRLBP<1:0>:** LCD Reference Ladder B Time Power Control bits
During Time interval B (Refer to Figure 18-4):
00 = Internal LCD Reference Ladder is powered down and unconnected
01 = Internal LCD Reference Ladder is powered in Low-Power mode
10 = Internal LCD Reference Ladder is powered in Medium-Power mode
11 = Internal LCD Reference Ladder is powered in High-Power mode

bit 3 **Unimplemented:** Read as ‘0’

bit 2-0 **LRLAT<2:0>:** LCD Reference Ladder A Time Interval Control bits
Sets the number of 32 kHz clocks that the A Time Interval Power mode is active

For type A waveforms (WFT = 0):

000 = Internal LCD Reference Ladder is always in ‘B’ Power mode
001 = Internal LCD Reference Ladder is in ‘A’ Power mode for 1 clock and ‘B’ Power mode for 15 clocks
010 = Internal LCD Reference Ladder is in ‘A’ Power mode for 2 clocks and ‘B’ Power mode for 14 clocks
011 = Internal LCD Reference Ladder is in ‘A’ Power mode for 3 clocks and ‘B’ Power mode for 13 clocks
100 = Internal LCD Reference Ladder is in ‘A’ Power mode for 4 clocks and ‘B’ Power mode for 12 clocks
101 = Internal LCD Reference Ladder is in ‘A’ Power mode for 5 clocks and ‘B’ Power mode for 11 clocks
110 = Internal LCD Reference Ladder is in ‘A’ Power mode for 6 clocks and ‘B’ Power mode for 10 clocks
111 = Internal LCD Reference Ladder is in ‘A’ Power mode for 7 clocks and ‘B’ Power mode for 9 clocks

For type B waveforms (WFT = 1):

000 = Internal LCD Reference Ladder is always in ‘B’ Power mode.
001 = Internal LCD Reference Ladder is in ‘A’ Power mode for 1 clock and ‘B’ Power mode for 31 clocks
010 = Internal LCD Reference Ladder is in ‘A’ Power mode for 2 clocks and ‘B’ Power mode for 30 clocks
011 = Internal LCD Reference Ladder is in ‘A’ Power mode for 3 clocks and ‘B’ Power mode for 29 clocks
100 = Internal LCD Reference Ladder is in ‘A’ Power mode for 4 clocks and ‘B’ Power mode for 28 clocks
101 = Internal LCD Reference Ladder is in ‘A’ Power mode for 5 clocks and ‘B’ Power mode for 27 clocks
110 = Internal LCD Reference Ladder is in ‘A’ Power mode for 6 clocks and ‘B’ Power mode for 26 clocks
111 = Internal LCD Reference Ladder is in ‘A’ Power mode for 7 clocks and ‘B’ Power mode for 25 clocks

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MOVIW **Move INDFn to W**

Syntax: [*label*] MOVIW ++FSRn
[*label*] MOVIW --FSRn
[*label*] MOVIW FSRn++
[*label*] MOVIW FSRn--
[*label*] MOVIW k[FSRn]

Operands: n ∈ [0,1]
mm ∈ [00,01, 10, 11]
-32 ≤ k ≤ 31

Operation: INDFn → W
Effective address is determined by
- FSR + 1 (preincrement)
- FSR - 1 (predecrement)
- FSR + k (relative offset)

After the Move, the FSR value will be either:
- FSR + 1 (all increments)
- FSR - 1 (all decrements)
- Unchanged

Status Affected: Z

Mode	Syntax	mm
Preincrement	++FSRn	00
Predecrement	--FSRn	01
Postincrement	FSRn++	10
Postdecrement	FSRn--	11

Description: This instruction is used to move data between W and one of the indirect registers (INDFn). Before/after this move, the pointer (FSRn) is updated by pre/post incrementing/decrementing it.

Note: The INDFn registers are not physical registers. Any instruction that accesses an INDFn register actually accesses the register at the address specified by the FSRn.

FSRn is limited to the range 0000h - FFFFh. Incrementing/decrementing it beyond these bounds will cause it to wrap-around.

MOVLB **Move literal to BSR**

Syntax: [*label*] MOVLB k

Operands: 0 ≤ k ≤ 15

Operation: k → BSR

Status Affected: None

Description: The 5-bit literal 'k' is loaded into the Bank Select Register (BSR).

MOVLP **Move literal to PCLATH**

Syntax: [*label*] MOVLP k

Operands: 0 ≤ k ≤ 127

Operation: k → PCLATH

Status Affected: None

Description: The 7-bit literal 'k' is loaded into the PCLATH register.

MOVLW **Move literal to W**

Syntax: [*label*] MOVLW k

Operands: 0 ≤ k ≤ 255

Operation: k → (W)

Status Affected: None

Description: The 8-bit literal 'k' is loaded into W register. The "don't cares" will assemble as '0's.

Words: 1

Cycles: 1

Example:
```
MOVLW   0x5A
```
After Instruction
W = 0x5A

MOVWF **Move W to f**

Syntax: [*label*] MOVWF f

Operands: 0 ≤ f ≤ 127

Operation: (W) → (f)

Status Affected: None

Description: Move data from W register to register 'f'.

Words: 1

Cycles: 1

Example:
```
MOVWF   OPTION_REG
```
Before Instruction
OPTION_REG = 0xFF
W = 0x4F
After Instruction
OPTION_REG = 0x4F
W = 0x4F

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SWAPF **Swap Nibbles in f**

Syntax:	[*label*] SWAPF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(f<3:0>) → (destination<7:4>), (f<7:4>) → (destination<3:0>)
Status Affected:	None
Description:	The upper and lower nibbles of register 'f' are exchanged. If 'd' is '0', the result is placed in the W register. If 'd' is '1', the result is placed in register 'f'.

TRIS **Load TRIS Register with W**

Syntax:	[*label*] TRIS f
Operands:	$5 \le f \le 7$
Operation:	(W) → TRIS register 'f'
Status Affected:	None
Description:	Move data from W register to TRIS register. When 'f' = 5, TRISA is loaded. When 'f' = 6, TRISB is loaded. When 'f' = 7, TRISC is loaded.

XORLW **Exclusive OR literal with W**

Syntax:	[*label*] XORLW k
Operands:	$0 \le k \le 255$
Operation:	(W) .XOR. k → (W)
Status Affected:	Z
Description:	The contents of the W register are XOR'ed with the 8-bit literal 'k'. The result is placed in the W register.

XORWF **Exclusive OR W with f**

Syntax:	[*label*] XORWF f,d
Operands:	$0 \le f \le 127$ $d \in [0,1]$
Operation:	(W) .XOR. (f) → (destination)
Status Affected:	Z
Description:	Exclusive OR the contents of the W register with register 'f'. If 'd' is '0', the result is stored in the W register. If 'd' is '1', the result is stored back in register 'f'.

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TABLE 21-4: I/O PORTS

DC CHARACTERISTICS			Standard Operating Conditions (unless otherwise stated)				
Param No.	Sym.	Characteristic	Min.	Typ†	Max.	Units	Conditions
	V_{IL}	**Input Low Voltage**					
		I/O PORT:					
D032		with TTL buffer	—	—	0.15 V_{DD}	V	1.8V ≤ V_{DD} ≤ 3.6V
D033		with Schmitt Trigger buffer	—	—	0.2 V_{DD}	V	1.8V ≤ V_{DD} ≤ 3.6V
D034		$\overline{MCLR}$, OSC1	—	—	0.2 V_{DD}	V	
	V_{IH}	**Input High Voltage**					
		I/O ports:					
D040		with TTL buffer	0.25 V_{DD} + 0.8	—	—	V	1.8V ≤ V_{DD} ≤ 3.6V
D041		with Schmitt Trigger buffer	0.8 V_{DD}	—	—	V	1.8V ≤ V_{DD} ≤ 3.6V
D042		$\overline{MCLR}$	0.8 V_{DD}	—	—	V	
	I_{IL}	**Input Leakage Current(2)**					
D060		I/O ports	—	± 5	± 125	nA	V_{SS} ≤ V_{PIN} ≤ V_{DD}, Pin at high-impedance @ 85°C
				± 5	± 1000	nA	125°C
D061		$\overline{MCLR}$(3)	—	± 50	± 200	nA	V_{SS} ≤ V_{PIN} ≤ V_{DD} @ 85°C
	I_{PUR}	**Weak Pull-up Current**					
D070*			25	100	200	µA	V_{DD} = 3.3V, V_{PIN} = V_{SS}
	V_{OL}	**Output Low Voltage**					
D080		I/O ports	—	—	0.6	V	I_{OL} = 6mA, V_{DD} = 3.3V I_{OL} = 1.8mA, V_{DD} = 1.8V
	V_{OH}	**Output High Voltage**					
D090		I/O ports	V_{DD} - 0.7	—	—	V	I_{OH} = 3mA, V_{DD} = 3.3V I_{OH} = 1mA, V_{DD} = 1.8V
		Capacitive Loading Specs on Output Pins					
D101*	C_{IO}	All I/O pins	—	—	50	pF	

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Negative current is defined as current sourced by the pin.

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TABLE 21-10: RESET, WATCHDOG TIMER, OSCILLATOR START-UP TIMER, POWER-UP TIMER AND BROWN-OUT RESET PARAMETERS

Standard Operating Conditions (unless otherwise stated)							
Param. No.	**Sym.**	**Characteristic**	**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
30	TMCL	$\overline{MCLR}$ Pulse Width (low)	2 5	— —	— —	µs µs	VDD = 3.0V, -40°C to +85°C VDD = 3.0V
31	FWDTLP	Low Frequency Internal Oscillator Frequency	19	33	52	kHz	
32	TOST	Oscillator Start-up Timer Period(1)	—	1024	—	Tosc	**(Note 2)**
33*	TPWRT	Power-up Timer Period, $\overline{PWRTE}$ = 0	—	2048	—	Tosc	Clocked by LFINTOSC
34*	TIOZ	I/O High-Impedance from $\overline{MCLR}$ Low or Watchdog Timer Reset	—	—	2.0	µs	
35	VBOR	Brown-out Reset Voltage: BORV = 0 BORV = 1	2.55 1.80	2.70 1.90	2.85 2.05	V V	
35A*	VHYST	Brown-out Reset Hysteresis	25 —	50 —	75 100	mV mV	-40°C to +85°C -40°C to +125°C
35B*	TBORDC	Brown-out Reset DC Response Time	1 —	3 —	5 10	µs µs	VDD ≤ VBOR, -40°C to +85°C VDD ≤ VBOR
35C	TBORAC	Brown-out Reset AC Response Time	—	100	—	ns	Transient Response immunity for a noise spike that goes from VDD to VSS and back with 10 ns rise and fall times. Guidance only.
36	TFVRS	Fixed Voltage Reference Turn-on Time	—	—	5	µs	Turn on to specified stability
37	VLPBOR	Low-Power Brown-out Reset Voltage	1.85	1.95	2.10	V	-40°C to +85°C
38*	VZPHYST	Zero-Power Brown-out Reset Hysteresis	0	25	60	mV	-40°C to +85°C
39*	TZPBPW	Zero-Power Brown-out Reset AC Response Time for BOR detection	10	—	500	nVs	VDD ≤ VBOR, -40°C to +85°C

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Instruction cycle period (TCY) equals four times the input oscillator time base period. All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. All devices are tested to operate at "min" values with an external clock applied to the OSC1 pin. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

2: Period of the slower clock.

3: To ensure these voltage tolerances, VDD and VSS must be capacitively decoupled as close to the device as possible. 0.1 µF and 0.01 µF values in parallel are recommended.

FIGURE 21-9: TIMER0 AND TIMER1 EXTERNAL CLOCK TIMINGS

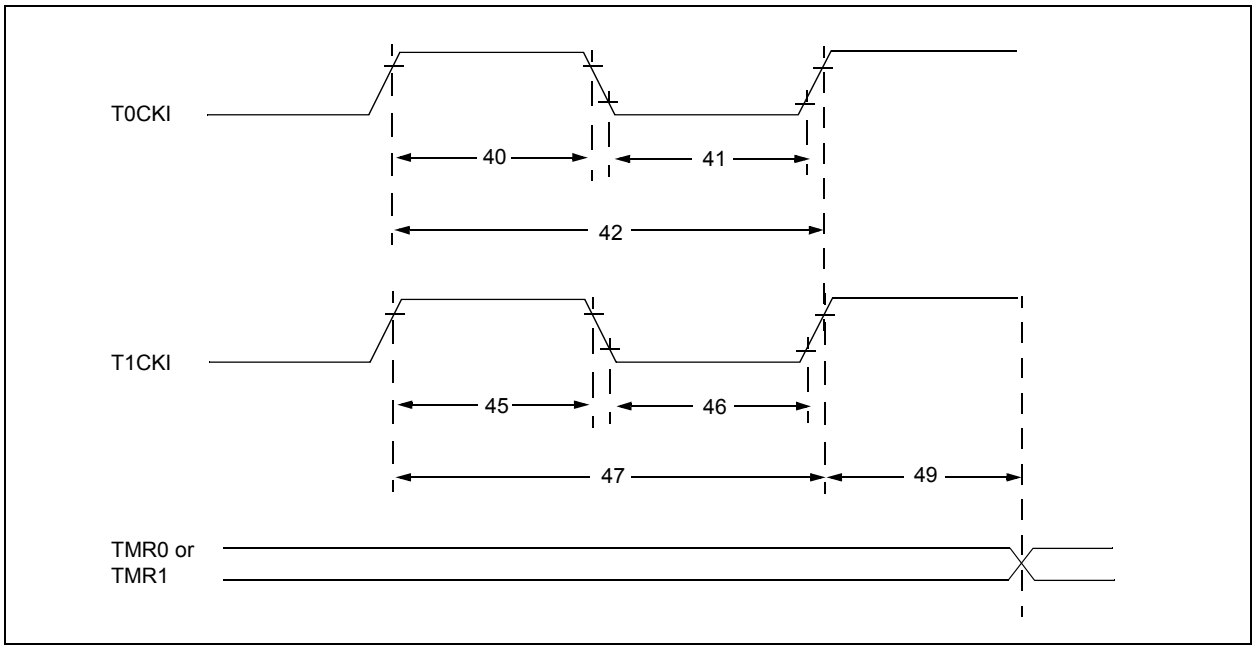

TABLE 21-11: TIMER0 AND TIMER1 EXTERNAL CLOCK REQUIREMENTS

Standard Operating Conditions(unless otherwise stated)								
Param No.	**Sym.**	**Characteristic**		**Min.**	**Typ†**	**Max.**	**Units**	**Conditions**
40*	TT0H	T0CKI High Pulse Width	No Prescaler	0.5 TCY + 20	—	—	ns	
			With Prescaler	10	—	—	ns	
41*	TT0L	T0CKI Low Pulse Width	No Prescaler	0.5 TCY + 20	—	—	ns	
			With Prescaler	10	—	—	ns	
42*	TT0P	T0CKI Period		Greater of: 20 or TCY + 40 N	—	—	ns	N = prescale value (2, 4, ..., 256)
45*	TT1H	T1CKI High Time	Synchronous, No Prescaler	0.5 TCY + 20	—	—	ns	
			Synchronous, with Prescaler	15	—	—	ns	
			Asynchronous	30	—	—	ns	
46*	TT1L	T1CKI Low Time	Synchronous, No Prescaler	0.5 TCY + 20	—	—	ns	
			Synchronous, with Prescaler	15	—	—	ns	
			Asynchronous	30	—	—	ns	
47*	TT1P	T1CKI Input Period	Synchronous	Greater of: 30 or TCY + 40 N	—	—	ns	N = prescale value (1, 2, 4, 8)
			Asynchronous	60	—	—	ns	
48	FT1	Timer1 Oscillator Input Frequency Range (oscillator enabled by setting bit T1OSCEN)		32.4	32.768	33.1	kHz	
49*	TCKEZTMR1	Delay from External Clock Edge to Timer Increment		2 TOSC	—	7 TOSC	—	Timers in Sync mode

* These parameters are characterized but not tested.

† Data in "Typ" column is at 3.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

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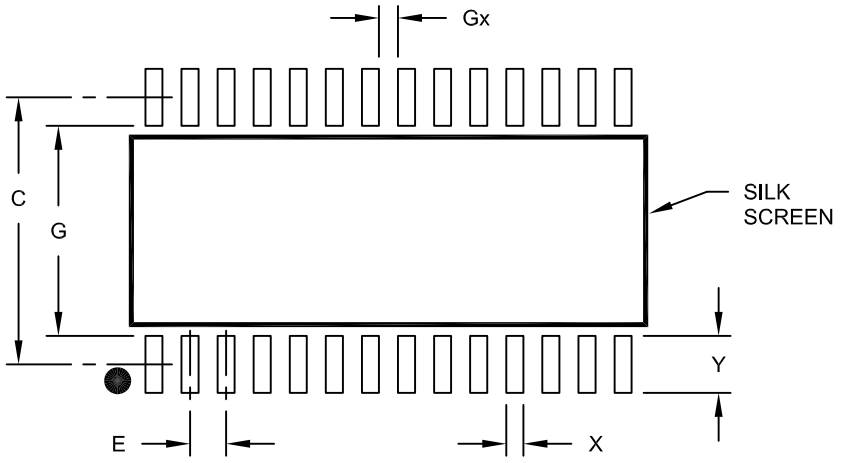
28-Lead Plastic Small Outline (SO) - Wide, 7.50 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	C		9.40	
Contact Pad Width (X28)	X			0.60
Contact Pad Length (X28)	Y			2.00
Distance Between Pads	Gx	0.67		
Distance Between Pads	G	7.40		

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2052A

APPENDIX A: DATA SHEET REVISION HISTORY

Revision A (01/2011)

Original release.

Revision B (04/2011)

Revised Sections: Flexible Oscillator Structure; Low-Power Features; Electrical Specifications; Changed ULPBOR to LPBOR.

Revision C (07/2014)

Updated Example 3-2, Register 4-2 and Table 5-1; Updated section 6, Oscillator Module, and section 9, Watchdog Timer; Updated table 10-3 and Figure 18-7; Removed Figure 19-1; Updated section 21, Electrical Specifications; Other minor corrections.

Revision D (04/2015)

Updated Equation 15-1; Figures 5-1, 18-7, 21-2, and 21-8; Register 4-2; Sections 4.1, 18.4.5, and 21.0; and Table 5-1, 9-2, 10-4, 21-1, and 21-10.

Revision E (01/2016)

Added ‘Memory’ section; Updated ‘PIC16LF1902/3 Family Types’ table; Other minor corrections.

Revision F (05/2016)

Updated Figure 21-2. Removed parameter 34A in Table 21-10. Removed Table 18-7, LCD Worksheet. Other minor corrections.

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